

Features

- Trench Power MOSFET
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free. "Green" Device (Note 1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)
- Moisture Sensitivity Level 1

Maximum Ratings

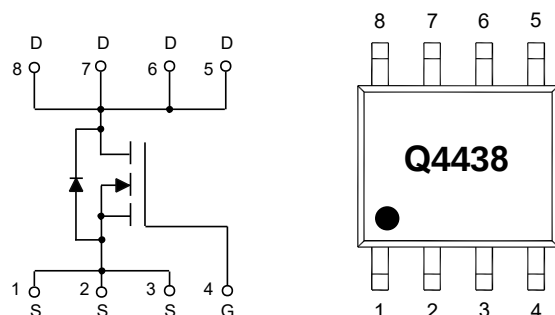
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 60°C/W Junction to Ambient (Note 2)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	8.2	A
		5	
Pulsed Drain Current (Note 3)	I_{DM}	40	A
Total Power Dissipation (Note 4)	P_D	2.1	W
Single Pulsed Avalanche Energy (Note 5)	E_{AS}	72	mJ

Note:

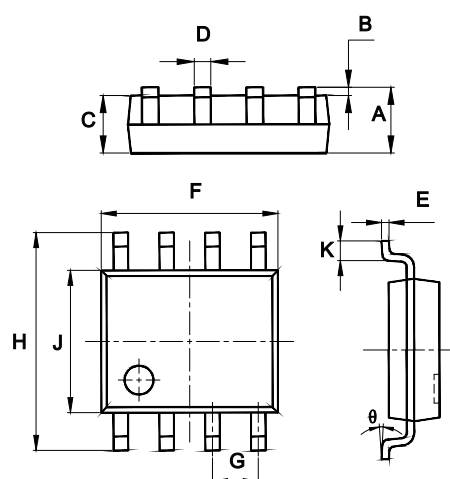
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The Power dissipation P_{DSM} is based on $R_{\theta JA} \leq 10\text{s}$ and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-Ambient thermal resistance.
5. $T_J = 25^\circ\text{C}$, $V_{DD} = 40\text{V}$, $V_{GS} = 10\text{V}$, $L = 1\text{mH}$.

Internal Structure and Marking Code



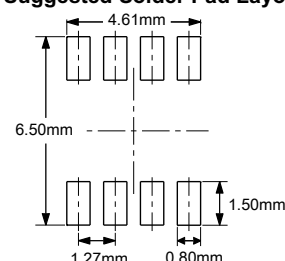
N-CHANNEL MOSFET

SOP-8



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.053	0.069	1.35	1.75	
B	0.004	0.010	0.10	0.25	
C	0.053	0.061	1.35	1.55	
D	0.013	0.020	0.33	0.51	
E	0.007	0.010	0.17	0.25	
F	0.185	0.200	4.70	5.10	
G	0.050		1.270		TYP.
H	0.228	0.244	5.80	6.20	
J	0.150	0.157	3.80	4.00	
K	0.016	0.050	0.40	1.27	
θ	0°	8°	0°	8°	

Suggested Solder Pad Layout



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	60			V
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			1	μA
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1		3	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =8.2A		13	22	mΩ
		V _{GS} =4.5V, I _D =7.6A		15.5	27	
Forward Tranconductance	g _{fs}	V _{DS} =5V, I _D =8.2A	10			S
Gate Resistance	R _G	f=1MHz, Open Drain		1.2		Ω
Dynamic Characteristics						
Continuous Body Diode Current	I _S				8.2	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =8.2A			1.2	V
Reverse Recovery Time	t _{rr}	I _S =20A, di/dt=100A/μs		24		ns
Reverse Recovery Charge	Q _{rr}			23		nC
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =30V, V _{GS} =0V, f=1MHz		2306		pF
Output Capacitance	C _{oss}			126		
Reverse Transfer Capacitance	C _{rss}			104		
Total Gate Charge(10V)	Q _g	V _{DS} =30V, V _{GS} =10V, I _D =8.2A		45		nC
Gate-Source Charge	Q _{gs}			5		
Gate-Drain Charge	Q _{gd}			9		
Turn-On Delay Time	t _{d(on)}	V _{GS} =10V, V _{DS} =30V, R _L =3.6Ω, R _{GEN} =3Ω		8.8		ns
Turn-On Rise Time	t _r			11		
Turn-Off Delay Time	t _{d(off)}			36		
Turn-Off Fall Time	t _f			7.7		

Fig. 1 - Typical Output Characteristics

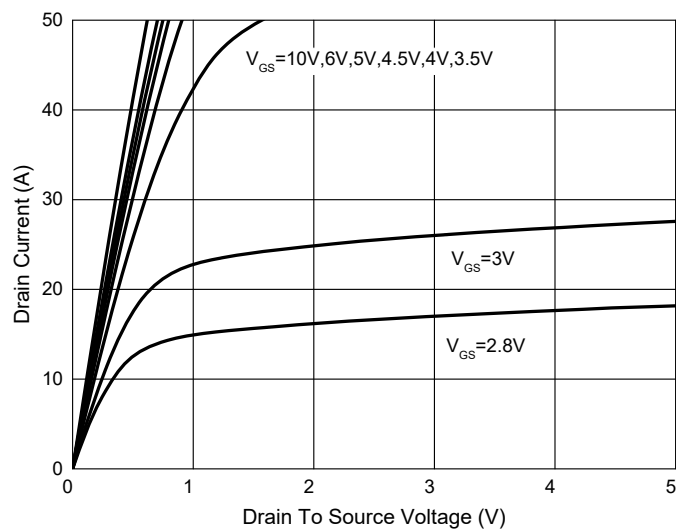


Fig. 2 - Transfer Characteristics

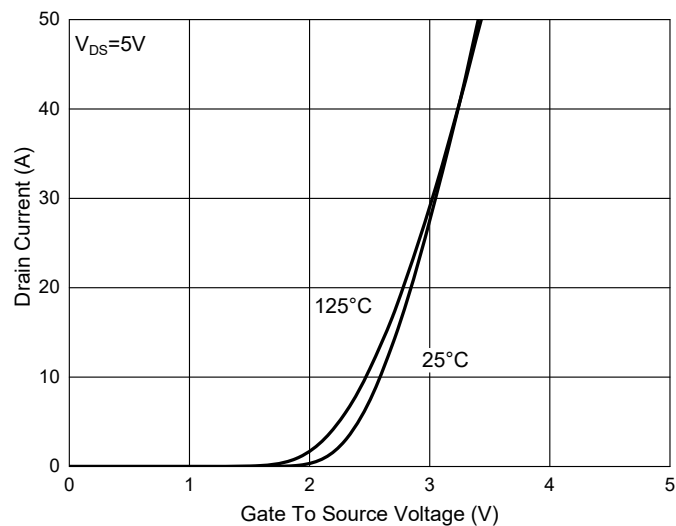


Fig. 3 - $R_{DS(ON)} - V_{GS}$

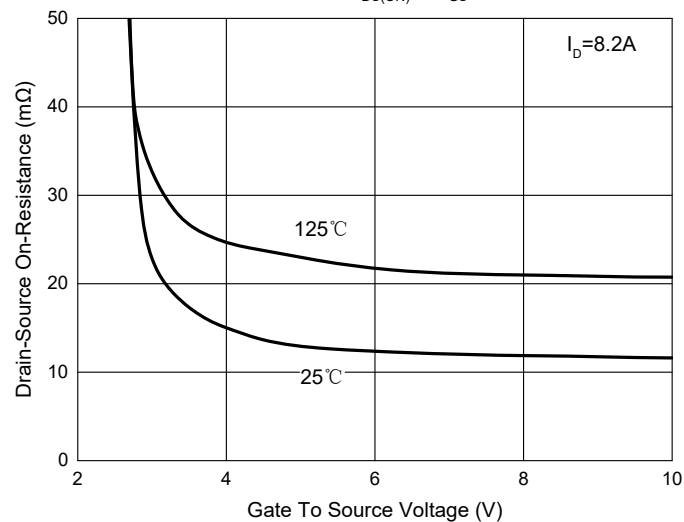


Fig. 4 - $R_{DS(ON)} - I_D$

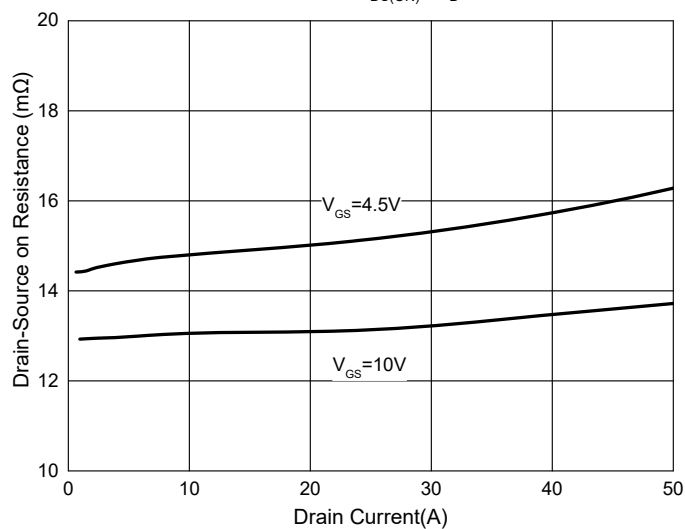


Fig. 5 - Capacitance Characteristics

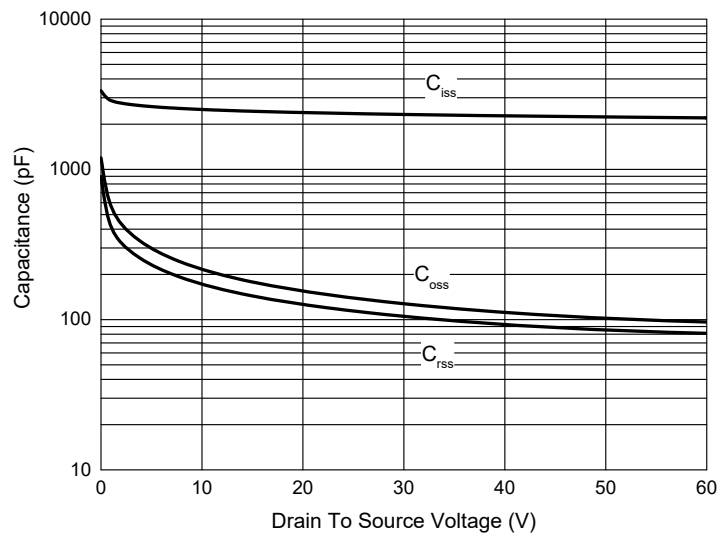
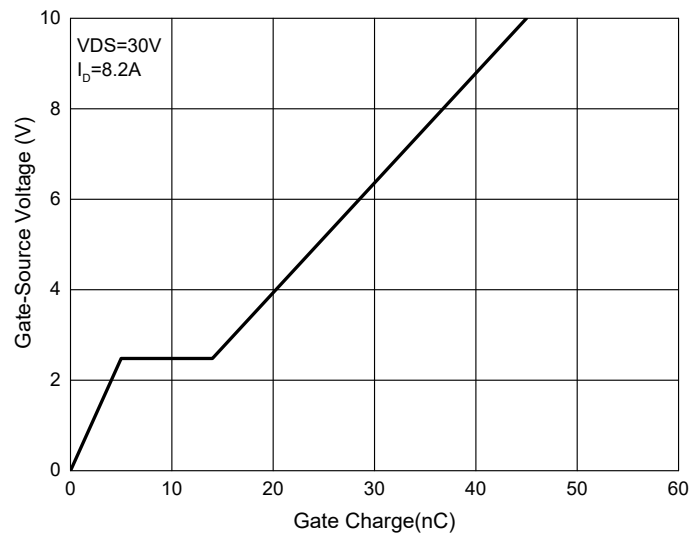


Fig. 6 - Gate Charge



Curve Characteristics

Fig. 7 - Normalized On Resistance Characteristics

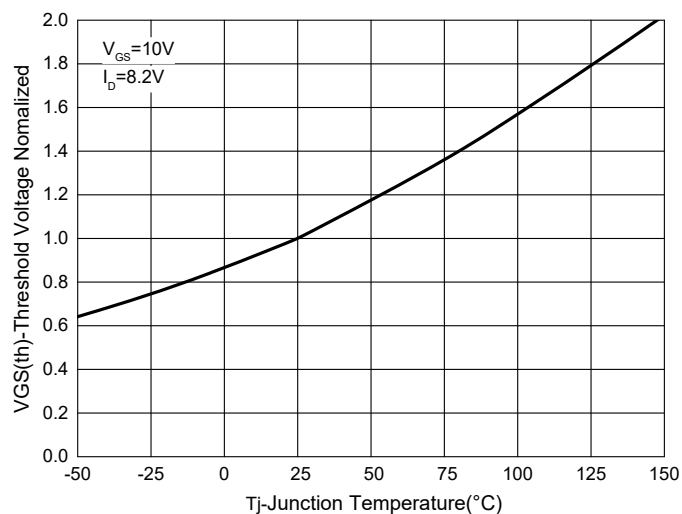


Fig. 8 - Normalized Threshold voltage

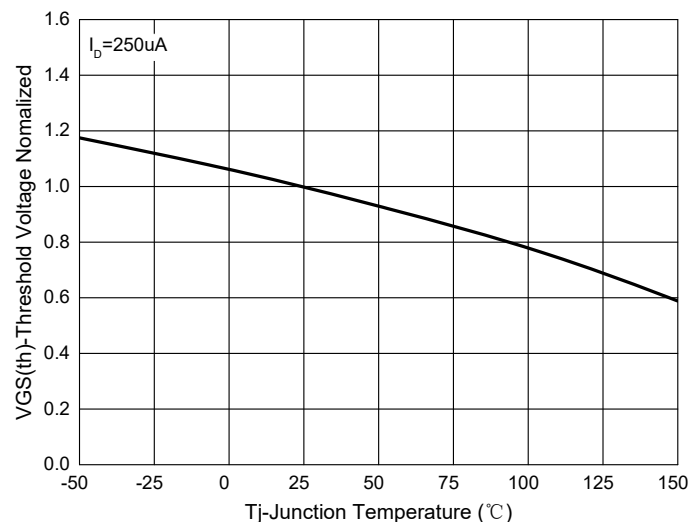


Fig. 9 - I_S — V_{SD}

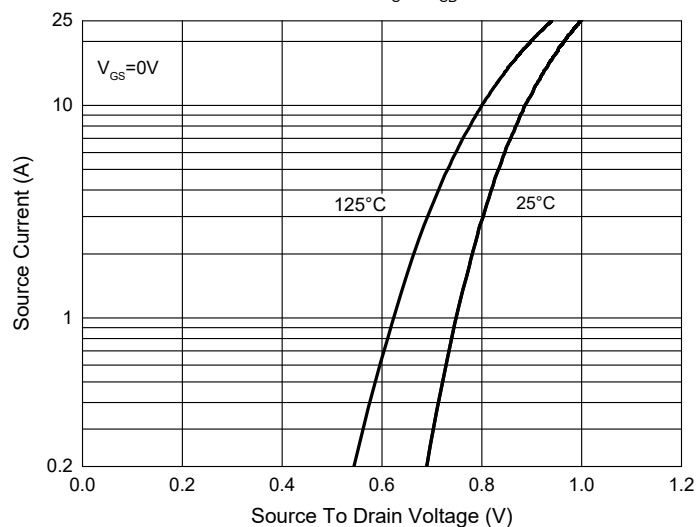


Fig. 10 - Drain Current

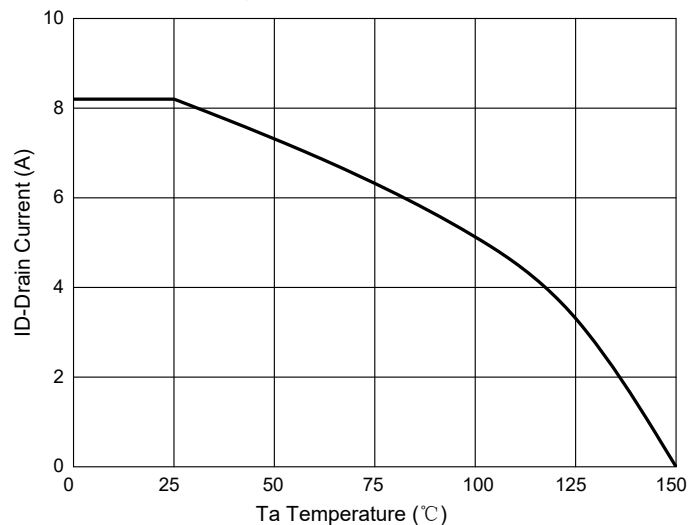
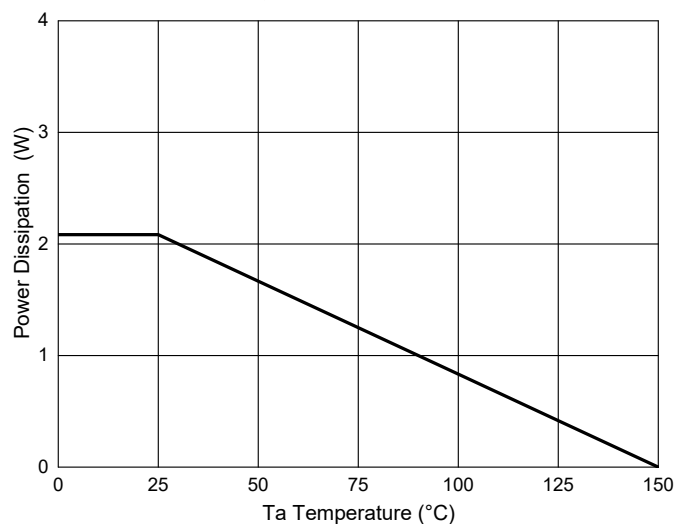


Fig.11-PD Dissipation



Curve Characteristics

Fig. 12 - Safe Operation Area

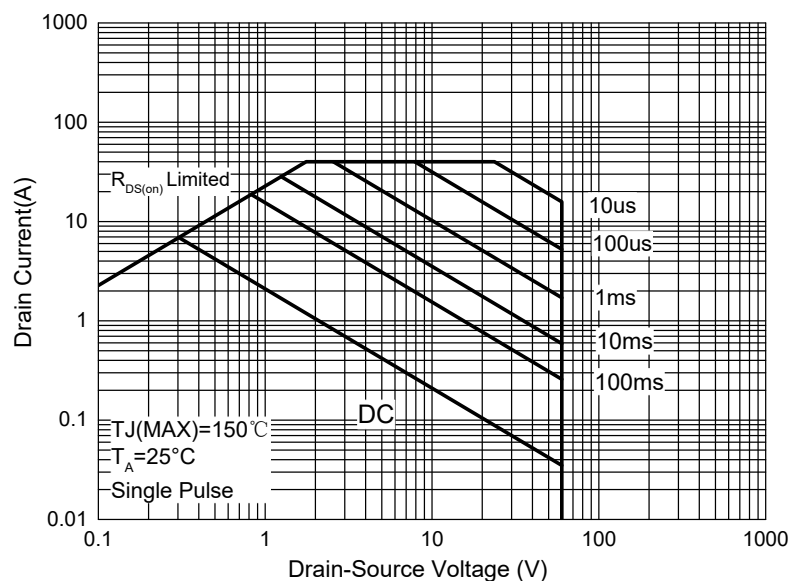
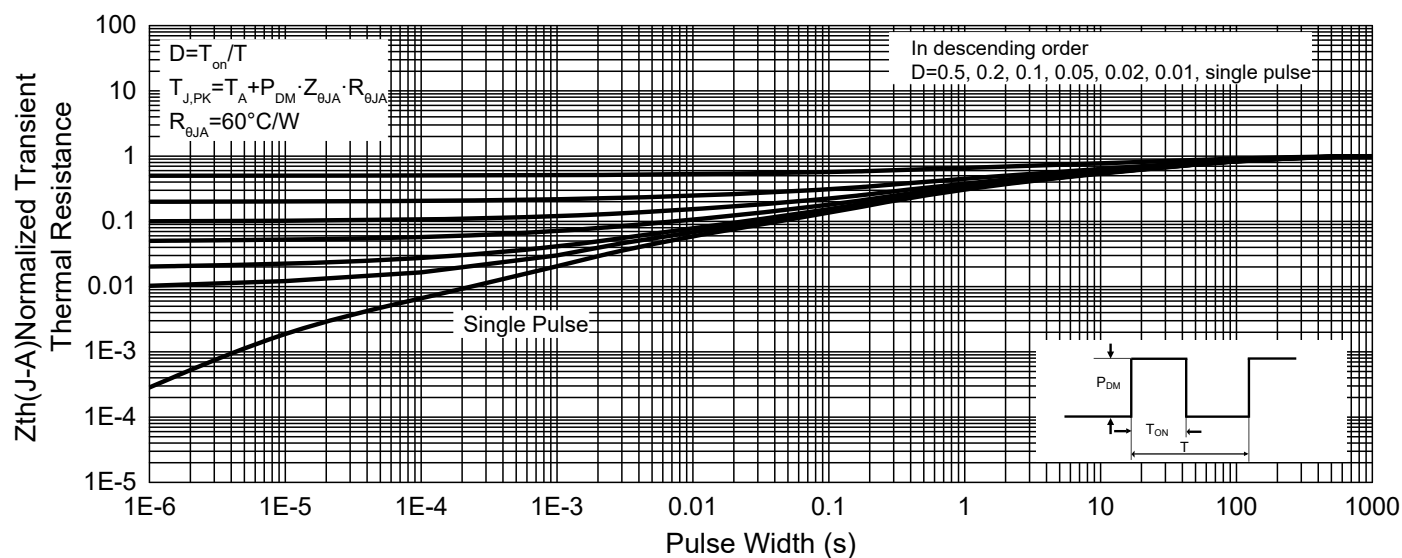


Fig. 13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 4Kpcs/Reel

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